RMB2F THRU RMB10F

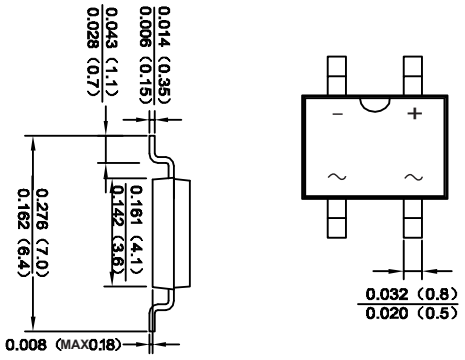
Voltage Range - 200 to 1000 Volts Current - 0.5/0.8 Ampere

GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Features

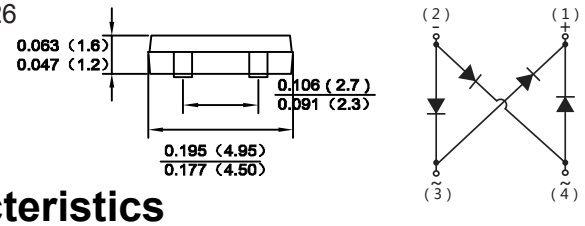
MBF

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°C /10 seconds at 5
- lbs., (2.3kg) tension Small size, simple installation
- Leads solderable per MIL-STD-202, Method 208
- High surge current capability
- Glass passivated chip junction
- Green compound(halogen&Sb2O3 free)



Mechanical Data

Case : JEDEC MBF Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0026 ounce, 0.075 grams



Maximum Ratings And Electrical Characteristics

Dimensions in inches and (millimeters)

Ratings at 25 °C ambient temperature unle ss otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter Marking Code	SYMBOLS	MDD RMB2F	MDD RMB4F	MDD RMB6F	MDD RMB8F	MDD RMB10F	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$	0.5 0.8					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F	1.3					V
Maximum DC reverse current T_A=25°C at rated DC blocking voltage T_A=100°C	I_R	5 0.5					uA mA
Maximum reverse recovery time	t_{rr}	150		250	200		ns
Typical thermal resistance Note3	$R\theta_{JL}$ $R\theta_{JA}$	30 88					°C/W
Operating temperature range Note4	T_J	-55 to +150					°C
storage temperature range	T_{STG}	-55 to +150					°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.
2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.
3.Thermal resistance form junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.
4.Reverse recovery condition I_F=0.5A,I_R=1.0A,Irr=0.25A.

Ratings And Characteristic Curves

FIG.1 FORWARD DERATING CURVE

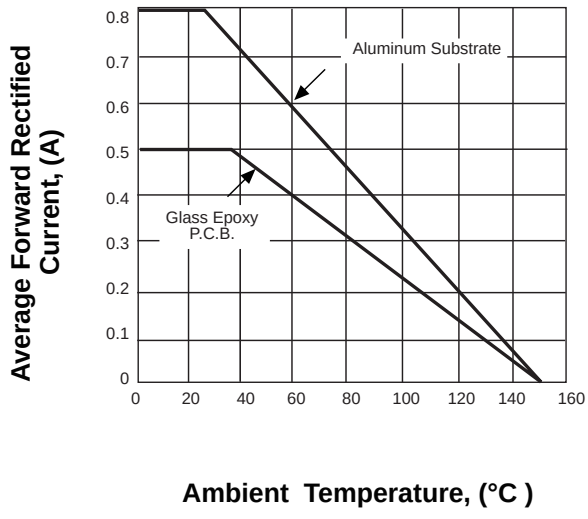


FIG.2 PEAK FORWARD SURGE CURRENT

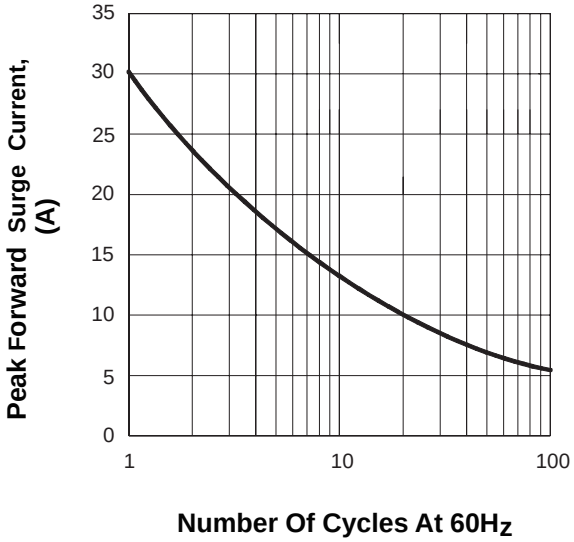


FIG.3 TYPICAL FORWARD CHARACTERISTICS

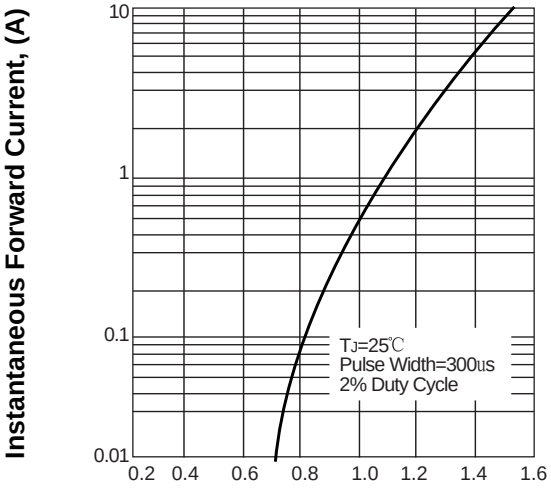
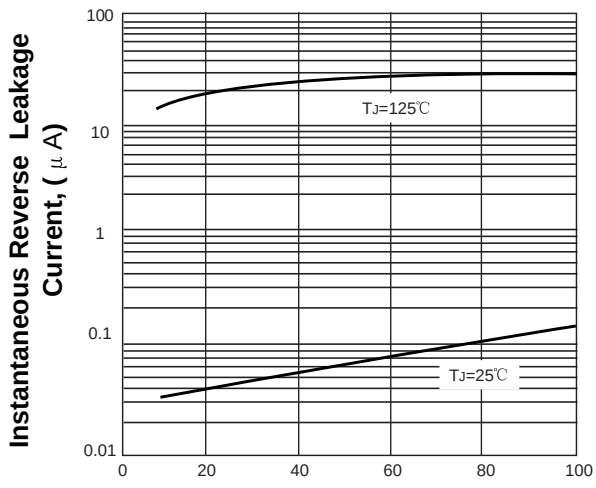
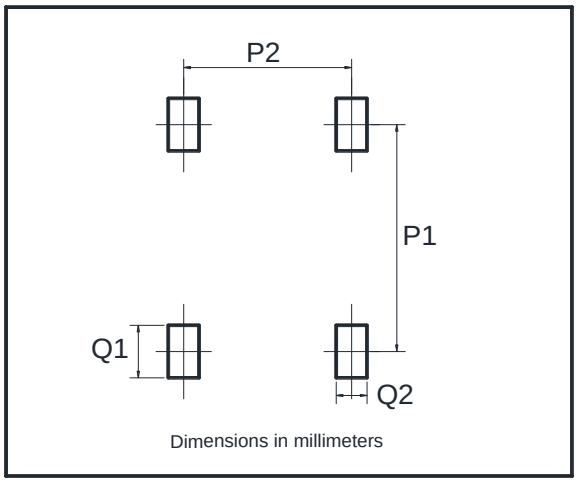


FIG.4 TYPICAL REVERSE CHARACTERISTICS



The curve above is for reference only.

Suggested Pad Layout



Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20